Metrics NA TC Chapter

Meeting Summary and Minutes

Thursday, February 12, 2026
1:00-3:00 PM Pacific
Online via Web Conference

TC Chapter Announcements

Next TC Chapter Meeting

Thursday, May 14, 2026

1:00-3:00 PM Eastern Time

ASMC

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: David Bouldin (Fab Consulting), Vladimir Kraz (OnFilter), Mark Frankfurth (Cymer)
SEMI Staff: Michelle Sun

Company	*Last*	*First*	*Company*	*Last*	*First*
BestESD Technical Services	*Kraz*	*Vladimir*	SEMI	*Sun*	*Michelle*
BIRD ELECTRONIC CORP	*Dummermuth*	*Martin*	Tokyo Electron Ltd.	*Mashiro*	*Supika*
Fab Consulting	*Bouldin*	*David*	Zama Consulting	*Sakamoto*	*Mitsune*
SCREEN セミコンダクターソリューションズ	*Futatsugi*	*Tetsuya*			

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
None		

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
None	

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
7436	Reapproval of SEMI E180-1220 - Test Method for Measuring Surface Metal Contamination Through ICP-MS of Critical Chamber Components Used in Semiconductor Wafer Processing	**Failed**

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
None			

Table 9 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
None			

Table 10 SNARF(s) Cancelled

#	*TF*	*Title*
None		

Table 11 Standard(s) to receive Inactive Status

Standard Designation	*Title*
None	

Table 12 New Action Items

Item #	*Assigned to*	*Details*
None		

Table 13 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
None		

1 Welcome, Reminders, and Introductions

David Bouldin (Fab Consulting) called the meeting to order at 1:18. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: Required Meeting Elements March 2024

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes as written
By / 2nd:	By: Vladimir Kraz (BestESD Technical Services) Second: Todor Ganev (KLA)
Discussion:	None
Vote:	6-Y 0-N

Attachment: IC-Minutes-Oct-2025

3 Liaison Reports

3.1 *Metrics Japan TC Chapter*

Michelle Sun (SEMI) reported for the Metrics Japan TC Chapter. Of note:

- Authorized Activities
  - 7435, Line-Item Revision of E113-0724 Specification for RF Power-Delivery Systems Used in Semiconductor Processing Equipment
- Task Force Highlights
  - Japan RF Measurement liaison Task Force
    - Doc.#6550A was approved with editorial changes by JA TC Chapter at its December 2023 meeting and published as E113-0724.
    - At the time of adjudication of Doc.#6550A, a couple comments deferred to future TF considerations, which was proposed as a Line-Item revision SNARF to the TC Chapter during JA TC Chapter meeting in December 2025

Attachment: 20260106_MetricsJapan_Liaison_Report_R1

3.2 *SEMI Staff Report*

Michelle Sun (SEMI) gave the SEMI Staff Report. Of note:

2026 Calendar of Events

Event Name	Event Details
SEMICON® KOREA	Feb 11-13 Seoul, Korea
SEMICON® CHINA	March 25-27 Shanghai, China
SEMIEXPO HEARTLAND	April 29-30 Detroit, Michigan
SEMICON® SOUTHEAST ASIA	May 05-07 Kuala Lumpur, Malaysia
SEMICON® TAIWAN	Sept 2-4 Taipei
SEMICON® INDIA	Sept 17-19 New Delhi

SEMICON West 2026-2030

- 2026—October 13-15 | Moscone Center | San Francisco, CA
- 2027—October 12-14 | Phoenix Convention Center | Phoenix, AZ
- 2028—October 10-12 | Moscone Center | San Francisco, CA
- 2029—October 9-11 | Phoenix Convention Center | Phoenix, AZ
- 2030—October 29-31 | Moscone Center | San Francisco, CA

Upcoming NA Meetings 2026

- NA Winter Meeting – Feb 9-12 via Web Conference
- NA Spring Meeting – May 11-14 at Albany, NY
- SEMICON West Meeting - October 12-15 at San Francisco, CA

ASMC Meeting Registration & Sponsorship

- Registration
  - Standards Meetings Registration
    - https://bit.ly/Standards_ASMC_2026
- Hotel Reservation
  - Hotel Link: https://www.hilton.com/en/attend-my-event/asmc-conference-may-2026/
  - Call 1(800) Hiltons reservation line and provide the code "4ASMC"
  - Deadline: Tuesday, April 21
- Sponsorship needed
  - Event Logistics (e.g., Catering, Coffee breaks, AV)
  - Please contact staff for more info.
- SEMI Advanced Semiconductor Manufacturing Conference (ASMC)
  - SEMI's international technical conference to discuss solutions that improve the collective manufacturing expertise of the semiconductor industry.
  - Provides a platform for semiconductor professionals to network and learn the latest in the practical application of advanced manufacturing strategies and methodologies.
- 14 New SEMI Standards Published in 2025
  - SEMI E192 – Guide for Equipment Adoption Criteria for GEM and GEM-related Standards
  - SEMI D87 – Test Method for Response Time Evaluation of Displays with Variable Refresh Rate
  - SEMI PV102 – Guide for Tube PECVD Graphite Boat Materials for Solar Cell Production
  - SEMI F122 – Guide for Facilities Data Package for Manufacturing Equipment Installation and Building Information Modeling
  - SEMI D88 – Specification for Electrostatic Properties of FPD Photomasks and Blanks Package
  - SEMI MS15 – Guide to MEMS Manufacturing Readiness Levels
  - SEMI E193 – Specification for 300 mm Film Frame FOUP (FFF)
  - SEMI M94 – Specification for Silicon Carbide Engineered Substrates
  - SEMI E194 – Guide to Using a Liquid Particle Counter to Assess Particulate Surface Contamination on Critical Chamber Components and Coupons

  - SEMI E195 – Test Method Using Adhesive Replacement Substrates to Assess Particulate Surface Contamination on Critical Chamber Components
  - SEMI E196 – Guide for Equipment Edge Data Governance
  - SEMI M95 – Test Method for Net Carrier Density and Resistivity of Silicon Epitaxial Layer by Capacitance–Voltage Measurements with an Evaporated Metal Schottky Diode
  - SEMI T26 – Specification for Electronic Supply Chain Traceability Using Distributed Ledger Technology
  - SEMI T27 – Specification for Traceability Identification Label of Component Parts
- Educational Courses under Development
  - {Subfab} Intro to Sub-fab Course
    - Objective: Gain a comprehensive understanding of SubFAB operations, including system components, facility layouts, environmental and sustainability considerations, organizational structure, safety and maintenance best practices, and incident-response preparedness within the semiconductor manufacturing ecosystem.
    - Course Date: Early 2026 (2 sessions, EU & Asia friendly)
  - Status: Under development
  - Other courses being considered: SECS/GEM, Seals, Cybersecurity

Attachment: Metrics_Staff_HQ Report Feb 2026 v3

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Document #7436, Reapproval of SEMI E180-1220 - Test Method for Measuring Surface Metal Contamination Through ICP-MS of Critical Chamber Components Used in Semiconductor Wafer Processing

Motion:	Negative is related and persuasive
Negative Text:	5.2.1: Update the CCC definition with the new agreed-upon definition as used in later CCC Standards (e.g., E195-0925)
By / 2nd:	By: Supika Mashiro (Tokyo Electron) Second: Vladimir Kraz (BestESD Technical Services)
Discussion:	None
Vote:	7-Y 0-N

Motion:	This Document failed TC Chapter review and will be returned to the TF for rework
By / 2nd:	By: Supika Mashiro (Tokyo Electron) Second: Todor Ganev (KLA)
Discussion:	None
Vote:	6-Y 0-N

5 Subcommittee and Task Force Reports

5.1 *Critical Chamber Components (CCC) Test Methods Task Force*

Supika Mashiro (TEL) reported for the CCC Task Force. This report contained information on ---- .

- Result of Letter Ballot on Document # 7436 Reapproval of SEMI E180
  - Doc.#7436 satisfied the minimum voting rate for Letter Ballot adjudication.
  - The ballot received Reject votes from David Bouldin/ Fab Consulting (8 Negatives) and Eric Sklar/ Safety Guru (23 Negatives)
  - TF recommends the TC Chapter to find David's Negative 5) "5.2.1: Update the CCC definition with the new agreed-upon definition as used in later CCC Standards (e.g., E195-0925)" to be related and persuasive.
- Discussion on 7167
  - The TF reviewed the latest #7167 draft and made various edits.

    - Title and Purpose sections were updated based on TF discussion.
    - Further review have been conducted and expected to continue until the TF feel it become ready for Letter Ballot
- Status of the “Overarching Document”
    - SNARF has been submitted and received FB.
    - TF move to ask SNARF approval.
    - The team of co-authors prepared draft of the “Overarching Document” for CCC TF review
    - The TF review is on hold waiting for author team’s responses to previously submitted FB from Eric.
    - Need clarification regarding role & responsibilities for the author(s) and TF leaders

Attachment: CCC Test Method TF Meeting TF Report_20260212

6 Next Meeting and Adjournment

The next meeting is tentatively scheduled for May 14, 2026, from 1:00-3:00 PM Pacific Time. See http://www.semi.org/standards-events for the current list of events.

Adjournment: 2:12

Respectfully submitted by:

Michelle Sun
Coordinator
SEMI North America
Phone: 408.943.7982
Email: msun@semi.org

Minutes tentatively approved by:

<Name> (<Company>), Co-chair	<Date approved>
<Name> (<Company>), Co-chair	<Date approved>

Table 14 Index of Available Attachments[#1]

Title	*Title*
Required Meeting Elements March 2024	CCC Test Method TF Meeting TF Report_20260212
IC-Minutes-Oct-2025	
20260106_MetricsJapan_Liaison_Report_R1	
Metrics_Staff_HQ Report Feb 2026 v3	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.